Infineon Technologies - C161PILF3VCAFXUMA1 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	76
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-1
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/c161pilf3vcafxuma1

C166 Family of C161PI
High-Performance CMOS 16-Bit Microcontrollers

Preliminary
C161PI 16-Bit Microcontroller

- High Performance 16-bit CPU with 4-Stage Pipeline
  - 80 ns Instruction Cycle Time at 25 MHz CPU Clock
  - 400 ns Multiplication (16 × 16 bit), 800 ns Division (32 / 16 bit)
  - Enhanced Boolean Bit Manipulation Facilities
  - Additional Instructions to Support HLL and Operating Systems
  - Register-Based Design with Multiple Variable Register Banks
  - Single-Cycle Context Switching Support
  - 16 MBytes Total Linear Address Space for Code and Data
  - 1024 Bytes On-Chip Special Function Register Area
- 16-Priority-Level Interrupt System with 27 Sources, Sample-Rate down to 40 ns
- 8-Channel Interrupt-Driven Single-Cycle Data Transfer Facilities via Peripheral Event Controller (PEC)
- Clk. Generation via on-chip PLL (1:1.5/2/2.5/3/4/5), via prescaler or via direct clk. inp.
- On-Chip Memory Modules
  - 1 KByte On-Chip Internal RAM (IRAM)
  - 2 KBytes On-Chip Extension RAM (XRAM)
- On-Chip Peripheral Modules
  - 4-Channel 10-bit A/D Converter with Programm. Conversion Time down to 7.8 µs
  - Two Multi-Functional General Purpose Timer Units with 5 Timers
  - Two Serial Channels (Synchronous/Asynchronous and High-Speed-Synchronous)
  - I^2C Bus Interface (10-bit Addressing, 400 KHz) with 2 Channels (multiplexed)
- Up to 8 MBytes External Address Space for Code and Data
  - Programmable External Bus Characteristics for Different Address Ranges
  - Multiplexed or Demultiplexed External Address/Data Buses with 8-Bit or 16-Bit Data Bus Width
  - Five Programmable Chip-Select Signals
- Idle and Power Down Modes with Flexible Power Management
- Programmable Watchdog Timer and Oscillator Watchdog
- On-Chip Real Time Clock
- Up to 76 General Purpose I/O Lines, partly with Selectable Input Thresholds and Hysteresis
- Supported by a Large Range of Development Tools like C-Compilers, Macro-Assembler Packages, Emulators, Evaluation Boards, HLL-Debuggers, Simulators, Logic Analyzer Disassemblers, Programming Boards
- On-Chip Bootstrap Loader
- 100-Pin MQFP / TQFP Package

Table 1 Pin Definitions and Functions (continued)

Symbol	Pin Num. TQFP	Pin Num. MQFP	Input Outp.	Function
$\overline{\text{RSTIN}}$	76	78	I/O	Reset Input with Schmitt-Trigger characteristics. A low level at this pin while the oscillator is running resets the C161PI. An internal pullup resistor permits power-on reset using only a capacitor connected to V_{SS}. A spike filter suppresses input pulses <10 ns. Input pulses >100 ns safely pass the filter. The minimum duration for a safe recognition should be 100 ns + 2 CPU clock cycles. In bidirectional reset mode (enabled by setting bit BDRSTEN in register SYSCON) the $\overline{\text{RSTIN}}$ line is internally pulled low for the duration of the internal reset sequence upon any reset (HW, SW, WDT). See note below this table. *Note: To let the reset configuration of PORT0 settle and to let the PLL lock a reset duration of ca. 1 ms is recommended.*
$\overline{\text{RSTOUT}}$	77	79	O	Internal Reset Indication Output. This pin is set to a low level when the part is executing either a hardware-, a software- or a watchdog timer reset. $\overline{\text{RSTOUT}}$ remains low until the EINIT (end of initialization) instruction is executed.
$\overline{\text{NMI}}$	78	80	I	Non-Maskable Interrupt Input. A high to low transition at this pin causes the CPU to vector to the NMI trap routine. When the PWRDN (power down) instruction is executed, the $\overline{\text{NMI}}$ pin must be low in order to force the C161PI to go into power down mode. If $\overline{\text{NMI}}$ is high, when PWRDN is executed, the part will continue to run in normal mode. If not used, pin $\overline{\text{NMI}}$ should be pulled high externally.

External Bus Controller

All of the external memory accesses are performed by a particular on-chip External Bus Controller (EBC). It can be programmed either to Single Chip Mode when no external memory is required, or to one of four different external memory access modes, which are as follows:

– 16-/18-/20-/23-bit Addresses, 16-bit Data, Demultiplexed
– 16-/18-/20-/23-bit Addresses, 16-bit Data, Multiplexed
– 16-/18-/20-/23-bit Addresses, 8-bit Data, Multiplexed
– 16-/18-/20-/23-bit Addresses, 8-bit Data, Demultiplexed

In the demultiplexed bus modes, addresses are output on PORT1 and data is input/ output on PORT0 or P0L, respectively. In the multiplexed bus modes both addresses and data use PORT0 for input/output.

Important timing characteristics of the external bus interface (Memory Cycle Time, Memory Tri-State Time, Length of ALE and Read Write Delay) have been made programmable to allow the user the adaption of a wide range of different types of memories and external peripherals.
In addition, up to 4 independent address windows may be defined (via register pairs ADDRSELx / BUSCONx) which allow to access different resources with different bus characteristics. These address windows are arranged hierarchically where BUSCON4 overrides BUSCON3 and BUSCON2 overrides BUSCON1. All accesses to locations not covered by these 4 address windows are controlled by BUSCON0.
Up to 5 external $\overline{CS}$ signals (4 windows plus default) can be generated in order to save external glue logic. The C161PI offers the possibility to switch the $\overline{CS}$ outputs to an unlatched mode. In this mode the internal filter logic is switched off and the $\overline{CS}$ signals are directly generated from the address. The unlatched $\overline{CS}$ mode is enabled by setting CSCFG (SYSCON.6).

Access to very slow memories is supported via a particular ‘Ready’ function.

For applications which require less than 8 MBytes of external memory space, this address space can be restricted to 1 MByte, 256 KByte or to 64 KByte. In this case Port 4 outputs four, two or no address lines at all. It outputs all 7 address lines, if an address space of 8 MBytes is used.

Serial Channels

Serial communication with other microcontrollers, processors, terminals or external peripheral components is provided by two serial interfaces with different functionality, an Asynchronous/Synchronous Serial Channel (**ASC0**) and a High-Speed Synchronous Serial Channel (**SSC**).

The ASC0 is upward compatible with the serial ports of the Infineon 8-bit microcontroller families and supports full-duplex asynchronous communication at up to 780 KBaud and half-duplex synchronous communication at up to 3.1 MBaud @ 25 MHz CPU clock.
A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling 4 separate interrupt vectors are provided. In asynchronous mode, 8- or 9-bit data frames are transmitted or received, preceded by a start bit and terminated by one or two stop bits. For multiprocessor communication, a mechanism to distinguish address from data bytes has been included (8-bit data plus wake up bit mode).
In synchronous mode, the ASC0 transmits or receives bytes (8 bits) synchronously to a shift clock which is generated by the ASC0. The ASC0 always shifts the LSB first. A loop back option is available for testing purposes.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. A parity bit can automatically be generated on transmission or be checked on reception. Framing error detection allows to recognize data frames with missing stop bits. An overrun error will be generated, if the last character received has not been read out of the receive buffer register at the time the reception of a new character is complete.

The SSC supports full-duplex synchronous communication at up to 6.25 Mbaud @ 25 MHz CPU clock. It may be configured so it interfaces with serially linked peripheral components. A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling 3 separate interrupt vectors are provided.
The SSC transmits or receives characters of 2...16 bits length synchronously to a shift clock which can be generated by the SSC (master mode) or by an external master (slave mode). The SSC can start shifting with the LSB or with the MSB and allows the selection of shifting and latching clock edges as well as the clock polarity.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. Transmit and receive error supervise the correct handling of the data buffer. Phase and baudrate error detect incorrect serial data.

Table 4 Instruction Set Summary (continued)

Mnemonic	Description	Bytes
MOV(B)	Move word (byte) data	2 / 4
MOVBS	Move byte operand to word operand with sign extension	2 / 4
MOVBZ	Move byte operand to word operand. with zero extension	2 / 4
JMPA, JMPI, JMPR	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
J(N)B	Jump relative if direct bit is (not) set	4
JBC	Jump relative and clear bit if direct bit is set	4
JNBS	Jump relative and set bit if direct bit is not set	4
CALLA, CALLI, CALLR	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH, POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack und update register with word operand	4
RET	Return from intra-segment subroutine	2
RETS	Return from inter-segment subroutine	2
RETP	Return from intra-segment subroutine and pop direct word register from system stack	2
RETI	Return from interrupt service subroutine	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Enter Power Down Mode (supposes $\overline{\text{NMI}}$-pin being low)	4
SRVWDT	Service Watchdog Timer	4
DISWDT	Disable Watchdog Timer	4
EINIT	Signify End-of-Initialization on RSTOUT-pin	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTended Register sequence	2
EXTP(R)	Begin EXTended Page (and Register) sequence	2 / 4
EXTS(R)	Begin EXTended Segment (and Register) sequence	2 / 4
NOP	Null operation	2

Parameter Interpretation

The parameters listed in the following partly represent the characteristics of the C161PI and partly its demands on the system. To aid in interpreting the parameters right, when evaluating them for a design, they are marked in column “Symbol”:

CC (**C**ontroller **C**haracteristics):
The logic of the C161PI will provide signals with the respective timing characteristics.

SR (**S**ystem **R**equirement):
The external system must provide signals with the respective timing characteristics to the C161PI.

DC Characteristics (Standard Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input low voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IL1} SR	– 0.5	0.3 V_{DD}	V	–
Input low voltage (TTL)	V_{IL} SR	– 0.5	0.2 V_{DD} – 0.1	V	–
Input low voltage (Special Threshold)	V_{ILS} SR	– 0.5	2.0	V	–
Input high voltage $\overline{\text{RSTIN}}$	V_{IH1} SR	0.6 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IH2} SR	0.7 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage (TTL)	V_{IH} SR	0.2 V_{DD} + 0.9	V_{DD} + 0.5	V	–
Input high voltage (Special Threshold)	V_{IHS} SR	0.8 V_{DD} - 0.2	V_{DD} + 0.5	V	–
Input Hysteresis (Special Threshold)	HYS	400	–	mV	–
Output low voltage (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$)	V_{OL} CC	–	0.45	V	I_{OL} = 2.4 mA
Output low voltage (P3.0, P3.1, P6.5, P6.6, P6.7)	V_{OL2} CC	–	0.4	V	I_{OL2} = 3 mA

DC Characteristics (Reduced Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input low voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IL1} SR	– 0.5	0.3 V_{DD}	V	–
Input low voltage (TTL)	V_{IL} SR	– 0.5	0.8	V	–
Input low voltage (Special Threshold)	V_{ILS} SR	– 0.5	1.3	V	–
Input high voltage $\overline{\text{RSTIN}}$	V_{IH1} SR	0.6 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IH2} SR	0.7 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage (TTL)	V_{IH} SR	1.8	V_{DD} + 0.5	V	–
Input high voltage (Special Threshold)	V_{IHS} SR	0.8 V_{DD} - 0.2	V_{DD} + 0.5	V	–
Input Hysteresis (Special Threshold)	HYS	250	–	mV	–
Output low voltage (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$)	V_{OL} CC	–	0.45	V	I_{OL} = 1.6 mA
Output low voltage P3.0, P3.1, P6.5, P6.6, P6.7	V_{OL2} CC	–	0.4	V	I_{OL2} = 1.6 mA
Output low voltage (all other outputs)	V_{OL1} CC	–	0.45	V	I_{OL} = 1.0 mA
Output high voltage [1] (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$)	V_{OH} CC	0.9 V_{DD}	–	V	I_{OH} = -0.5 mA
Output high voltage [1] (all other outputs)	V_{OH1} CC	0.9 V_{DD}	–	V	I_{OH} = -0.25 mA
Input leakage current (Port 5)	I_{OZ1} CC	–	±200	nA	0.45V < V_{IN} < V_{DD}
Input leakage current (all other)	I_{OZ2} CC	–	±500	nA	0.45V < V_{IN} < V_{DD}
$\overline{\text{RSTIN}}$ inactive current [2]	I_{RSTH} [3]	–	-10	µA	V_{IN} = V_{IH1}

AC Characteristics
Definition of Internal Timing

The internal operation of the C161PI is controlled by the internal CPU clock f_{CPU}. Both edges of the CPU clock can trigger internal (e.g. pipeline) or external (e.g. bus cycles) operations.

The specification of the external timing (AC Characteristics) therefore depends on the time between two consecutive edges of the CPU clock, called “TCL” (see figure below).

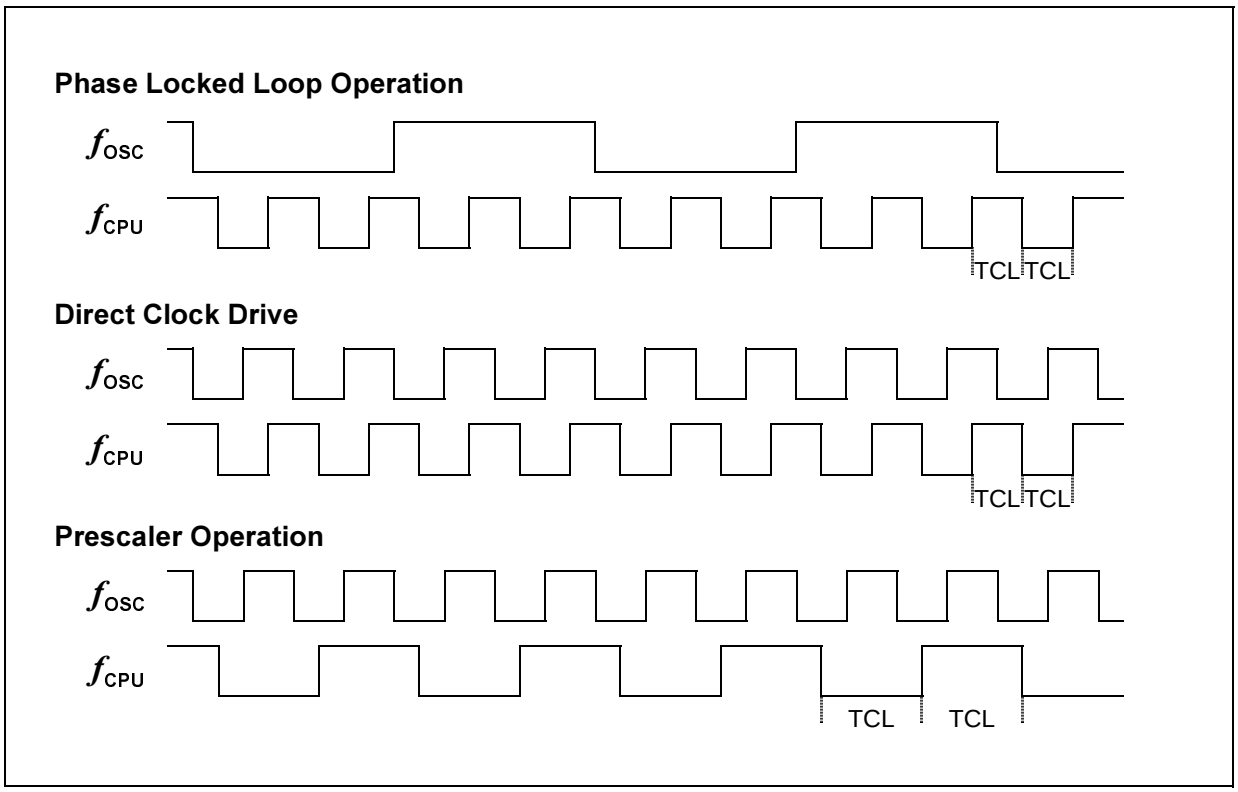

Figure 11 Generation Mechanisms for the CPU Clock

The CPU clock signal f_{CPU} can be generated from the oscillator clock signal f_{OSC} via different mechanisms. The duration of TCLs and their variation (and also the derived external timing) depends on the used mechanism to generate f_{CPU}. This influence must be regarded when calculating the timings for the C161PI.

Note: The example for PLL operation shown in the fig. above refers to a PLL factor of 4.

The used mechanism to generate the CPU clock is selected during reset via the logic levels on pins P0.15-13 (P0H.7-5).

The table below associates the combinations of these three bits with the respective clock generation mode.

The timings listed in the AC Characteristics that refer to TCLs therefore must be calculated using the minimum TCL that is possible under the respective circumstances.

The actual minimum value for TCL depends on the jitter of the PLL. As the PLL is constantly adjusting its output frequency so it corresponds to the applied input frequency (crystal or oscillator) the relative deviation for periods of more than one TCL is lower than for one single TCL (see formula and figure below).
For a period of ***N*** * TCL the minimum value is computed using the corresponding deviation D_N:

$(N * TCL)_{min} = N * TCL_{NOM} - D_N$ $\quad D_N\,[ns] = \pm(13.3 + N*6.3) / f_{CPU}\,[MHz]$,
where ***N*** = number of consecutive TCLs $\quad$ and $1 \le N \le 40$.

So for a period of 3 TCLs @ 25 MHz (i.e. ***N*** = 3): $D_3 = (13.3 + 3 * 6.3) / 25 = 1.288$ ns, and $(3TCL)_{min} = 3TCL_{NOM} - 1.288$ ns = 58.7 ns (@ f_{CPU} = 25 MHz).

This is especially important for bus cycles using waitstates and e.g. for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is neglectible.

Note: For all periods longer than 40 TCL the N=40 value can be used (see figure below).

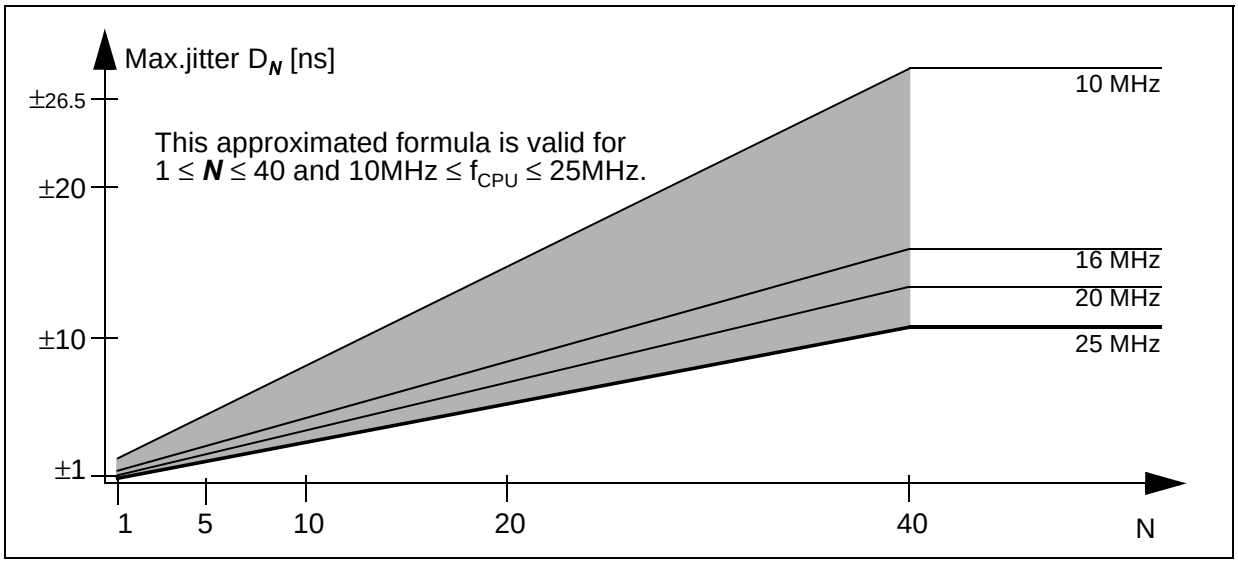

Figure 12 Approximated Maximum Accumulated PLL Jitter

A/D Converter Characteristics

(Operating Conditions apply)

4.0V (2.6V) ≤ V_{AREF} ≤ V_{DD} + 0.1V (Note the influence on TUE.)

V_{SS} - 0.1V ≤ V_{AGND} ≤ V_{SS} + 0.2V

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Analog input voltage range	V_{AIN} SR	V_{AGND}	V_{AREF}	V	1)
Basic clock frequency	f_{BC}	0.5	6.25	MHz	2)
Conversion time	t_C CC	–	40 t_{BC} + t_S+2t_{CPU}		3) t_{CPU} = 1 / f_{CPU}
Total unadjusted error	TUE CC 4)	–	± 2	LSB	V_{AREF} ≥ 4.0 V 5)
		–	± 4	LSB	V_{AREF} ≥ 2.6 V
Internal resistance of reference voltage source	R_{AREF} SR	–	t_{BC} / 60 - 0.25	kΩ	t_{BC} in [ns] 6) 7)
Internal resistance of analog source	R_{ASRC} SR	–	t_S / 450 - 0.25	kΩ	t_S in [ns] 7) 8)
ADC input capacitance	C_{AIN} CC	–	33	pF	7)

1) V_{AIN} may exceed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be $X000_H$ or $X3FF_H$, respectively.

2) The limit values for f_{BC} must not be exceeded when selecting the CPU frequency and the ADCTC setting.

3) This parameter includes the sample time t_S, the time for determining the digital result and the time to load the result register with the conversion result.
Values for the basic clock t_{BC} depend on the conversion time programming.
This parameter depends on the ADC control logic. It is not a real maximum value, but rather a fixum.

4) TUE is tested at V_{AREF}=5.0V (3.3V), V_{AGND}=0V, V_{DD}=4.9V (3.2V). It is guaranteed by design for all other voltages within the defined voltage range.
The specified TUE is guaranteed only if an overload condition (see I_{OV} specification) occurs on maximum 2 not selected analog input pins and the absolute sum of input overload currents on all analog input pins does not exceed 10 mA.
During the reset calibration sequence the maximum TUE may be ±4 LSB (±8 LSB @ 3V).

5) This case is not applicable for the reduced supply voltage range.

6) During the conversion the ADC's capacitance must be repeatedly charged or discharged. The internal resistance of the reference voltage source must allow the capacitance to reach its respective voltage level within each conversion step. The maximum internal resistance results from the programmed conversion timing.

7) Not 100% tested, guaranteed by design.

8) During the sample time the input capacitance C_I can be charged/discharged by the external source. The internal resistance of the analog source must allow the capacitance to reach its final voltage level within t_S. After the end of the sample time t_S, changes of the analog input voltage have no effect on the conversion result. Values for the sample time t_S depend on programming and can be taken from the table below.

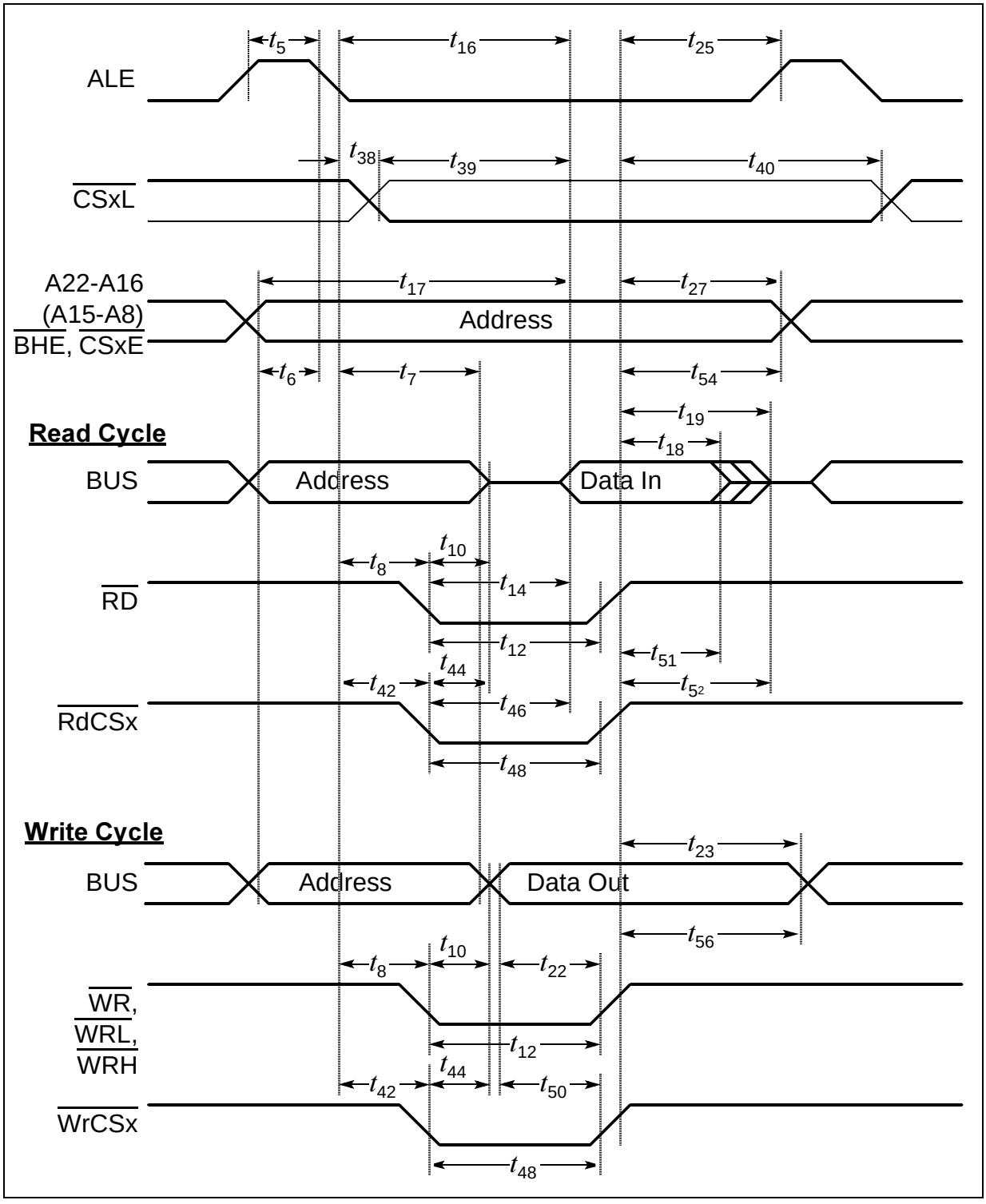

Figure 16 External Memory Cycle: Multiplexed Bus, With Read/Write Delay, Normal ALE

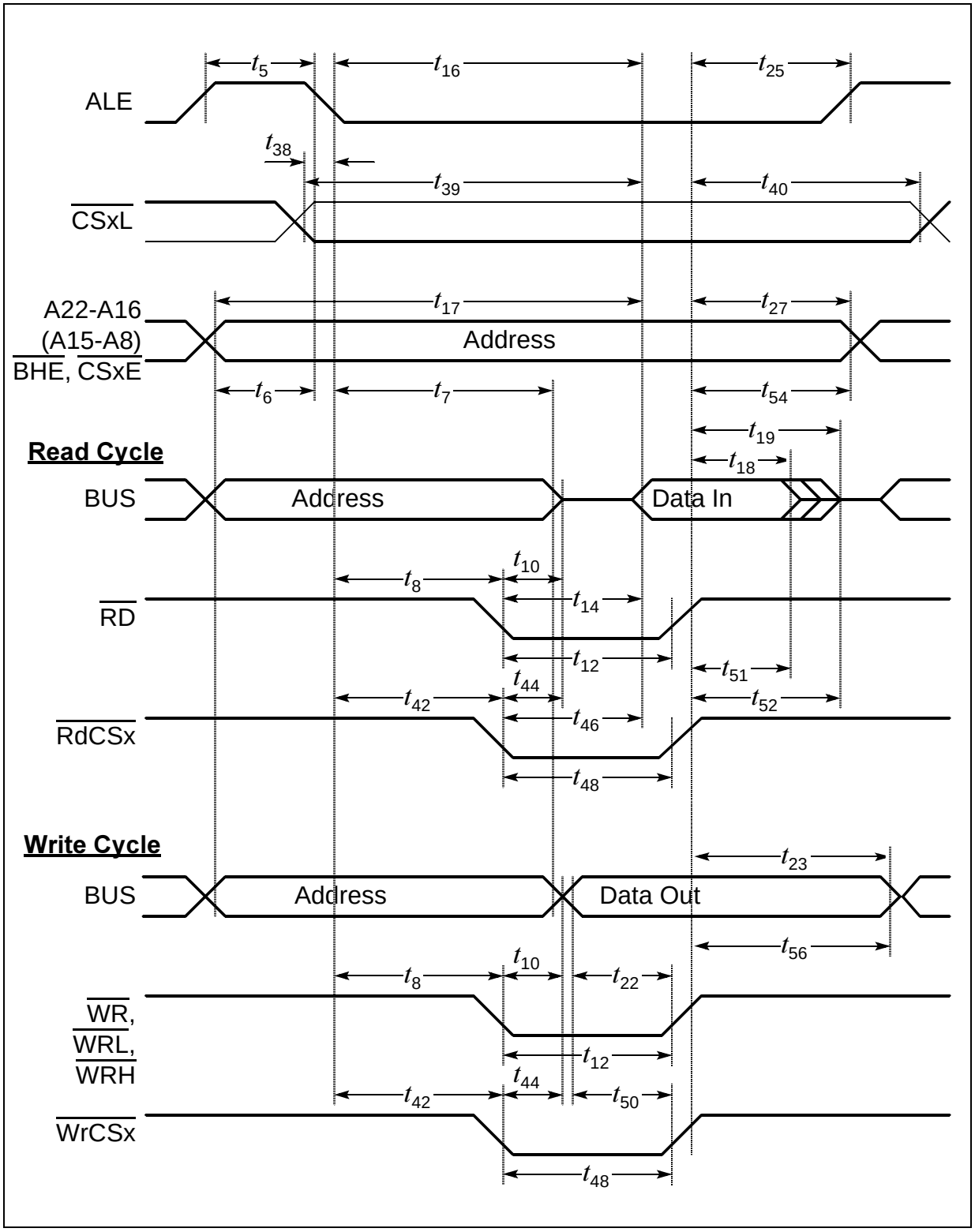

Figure 17 External Memory Cycle:
Multiplexed Bus, With Read/Write Delay, Extended ALE

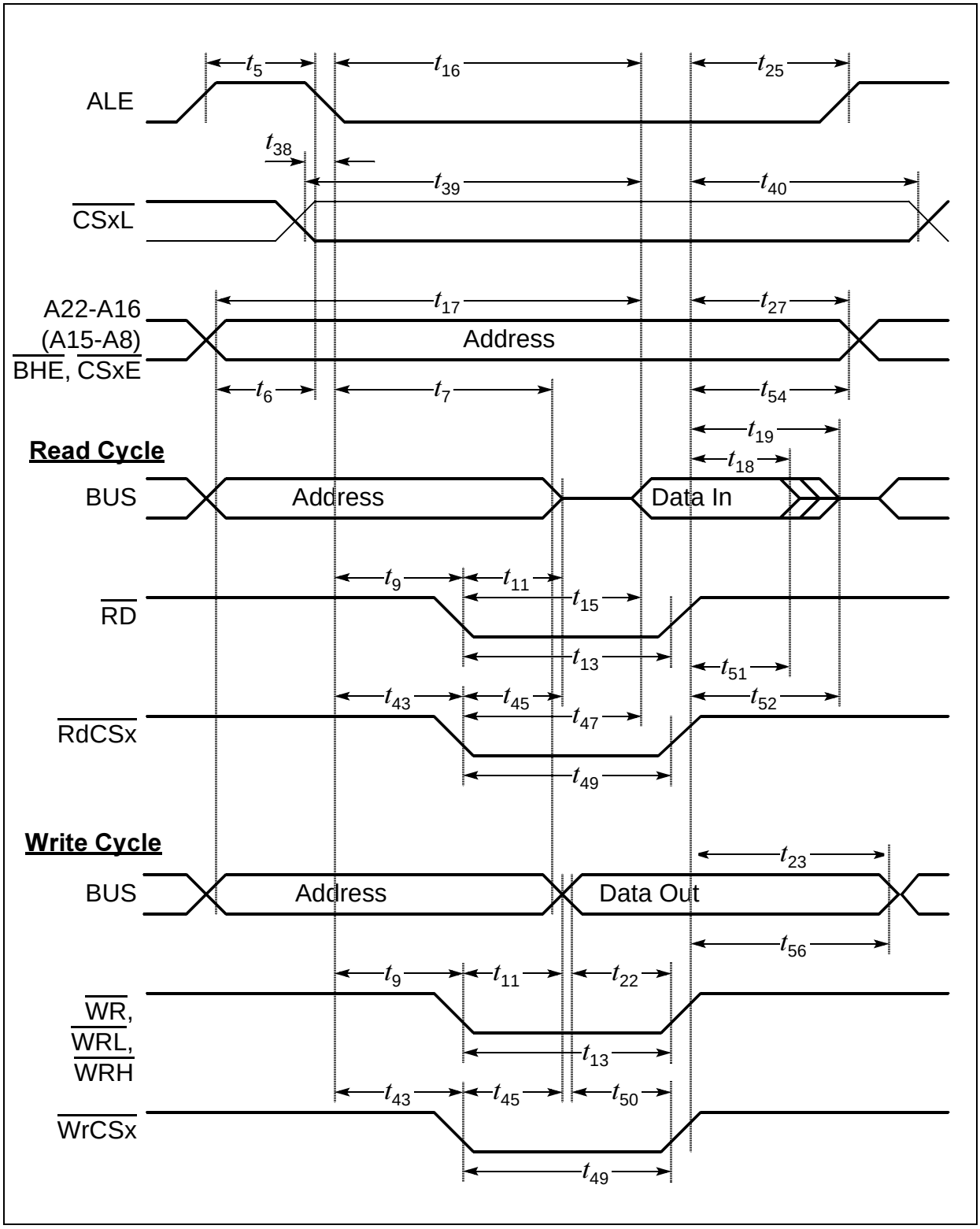

Figure 19 External Memory Cycle:
Multiplexed Bus, No Read/Write Delay, Extended ALE

AC Characteristics

Demultiplexed Bus (Standard Supply Voltage Range)

(Operating Conditions apply)

ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
ALE high time	t_5	CC	10 + t_A	–	TCL - 10 + t_A	–	ns
Address setup to ALE	t_6	CC	4 + t_A	–	TCL - 16 + t_A	–	ns
ALE falling edge to $\overline{RD}$, $\overline{WR}$ (with RW-delay)	t_8	CC	10 + t_A	–	TCL - 10 + t_A	–	ns
ALE falling edge to $\overline{RD}$, $\overline{WR}$ (no RW-delay)	t_9	CC	-10 + t_A	–	-10 + t_A	–	ns
$\overline{RD}$, $\overline{WR}$ low time (with RW-delay)	t_{12}	CC	30 + t_C	–	2TCL - 10 + t_C	–	ns
$\overline{RD}$, $\overline{WR}$ low time (no RW-delay)	t_{13}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns
$\overline{RD}$ to valid data in (with RW-delay)	t_{14}	SR	–	20 + t_C	–	2TCL - 20 + t_C	ns
$\overline{RD}$ to valid data in (no RW-delay)	t_{15}	SR	–	40 + t_C	–	3TCL - 20 + t_C	ns
ALE low to valid data in	t_{16}	SR	–	40 + t_A + t_C	–	3TCL - 20 + t_A + t_C	ns
Address to valid data in	t_{17}	SR	–	50 + 2t_A + t_C	–	4TCL - 30 + 2t_A + t_C	ns
Data hold after $\overline{RD}$ rising edge	t_{18}	SR	0	–	0	–	ns
Data float after $\overline{RD}$ rising edge (with RW-delay [1])	t_{20}	SR	–	26 + 2t_A + t_F [1]	–	2TCL - 14 + 22t_A + t_F [1]	ns
Data float after $\overline{RD}$ rising edge (no RW-delay [1])	t_{21}	SR	–	10 + 2t_A + t_F [1]	–	TCL - 10 + 22t_A + t_F [1]	ns
Data valid to $\overline{WR}$	t_{22}	CC	20 + t_C	–	2TCL - 20 + t_C	–	ns

Demultiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
Data hold after $\overline{WR}$	t_{24}	CC	10 + t_F	–	TCL - 10 + t_F	–	ns
$\overline{ALE}$ rising edge after $\overline{RD}$, $\overline{WR}$	t_{26}	CC	-10 + t_F	–	-10 + t_F	–	ns
Address hold after $\overline{WR}$ [2]	t_{28}	CC	0 + t_F	–	0 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{CS}$ [3]	t_{38}	CC	-4 - t_A	10 - t_A	-4 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In [3]	t_{39}	SR	–	40 + t_C + 2t_A	–	3TCL - 20 + t_C + 2t_A	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ [3]	t_{41}	CC	6 + t_F	–	TCL - 14 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW-delay)	t_{42}	CC	16 + t_A	–	TCL - 4 + t_A	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW-delay)	t_{43}	CC	-4 + t_A	–	-4 + t_A	–	ns
$\overline{RdCS}$ to Valid Data In (with RW-delay)	t_{46}	SR	–	16 + t_C	–	2TCL - 24 + t_C	ns
$\overline{RdCS}$ to Valid Data In (no RW-delay)	t_{47}	SR	–	36 + t_C	–	3TCL - 24 + t_C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW-delay)	t_{48}	CC	30 + t_C	–	2TCL - 10 + t_C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW-delay)	t_{49}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns
Data valid to $\overline{WrCS}$	t_{50}	CC	26 + t_C	–	2TCL - 14 + t_C	–	ns
Data hold after $\overline{RdCS}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{RdCS}$ (with RW-delay) [1]	t_{53}	SR	–	20 + t_F	–	2TCL - 20 + 2t_A + t_F [1]	ns
Data float after $\overline{RdCS}$ (no RW-delay) [1]	t_{68}	SR	–	0 + t_F	–	TCL - 20 + 2t_A + t_F [1]	ns

Demultiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
		min.	max.	min.	max.	
Address hold after RdCS, WrCS	t_{55} CC	-6 + t_F	–	-6 + t_F	–	ns
Data hold after WrCS	t_{57} CC	6 + t_F	–	TCL - 14 + t_F	–	ns

1) RW-delay and t_A refer to the next following bus cycle (including an access to an on-chip X-Peripheral).

2) Read data are latched with the same clock edge that triggers the address change and the rising RD edge. Therefore address changes before the end of RD have no impact on read cycles.

3) These parameters refer to the latched chip select signals (CSxL). The early chip select signals (CSxE) are specified together with the address and signal BHE (see figures below).

Demultiplexed Bus (Reduced Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
			min.	max.	min.	max.	
Data hold after $\overline{WR}$	t_{24}	CC	15 + t_F	–	TCL - 10 + t_F	–	ns
$\overline{ALE}$ rising edge after $\overline{RD}$, $\overline{WR}$	t_{26}	CC	-12 + t_F	–	-12 + t_F	–	ns
Address hold after $\overline{WR}$ [2]	t_{28}	CC	0 + t_F	–	0 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{CS}$ [3]	t_{38}	CC	-8 - t_A	10 - t_A	-8 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In [3]	t_{39}	SR	–	47 + t_C + 2t_A	–	3TCL - 28 + t_C + 2t_A	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ [3]	t_{41}	CC	9 + t_F	–	TCL - 16 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW-delay)	t_{42}	CC	19 + t_A	–	TCL - 6 + t_A	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW-delay)	t_{43}	CC	-6 + t_A	–	-6 + t_A	–	ns
$\overline{RdCS}$ to Valid Data In (with RW-delay)	t_{46}	SR	–	20 + t_C	–	2TCL - 30 + t_C	ns
$\overline{RdCS}$ to Valid Data In (no RW-delay)	t_{47}	SR	–	45 + t_C	–	3TCL - 30 + t_C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW-delay)	t_{48}	CC	38 + t_C	–	2TCL - 12 + t_C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW-delay)	t_{49}	CC	63 + t_C	–	3TCL - 12 + t_C	–	ns
Data valid to $\overline{WrCS}$	t_{50}	CC	28 + t_C	–	2TCL - 22 + t_C	–	ns
Data hold after $\overline{RdCS}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{RdCS}$ (with RW-delay) [1]	t_{53}	SR	–	30 + t_F	–	2TCL - 20 + 2t_A + t_F [1]	ns
Data float after $\overline{RdCS}$ (no RW-delay) [1]	t_{68}	SR	–	5 + t_F	–	TCL - 20 + 2t_A + t_F [1]	ns

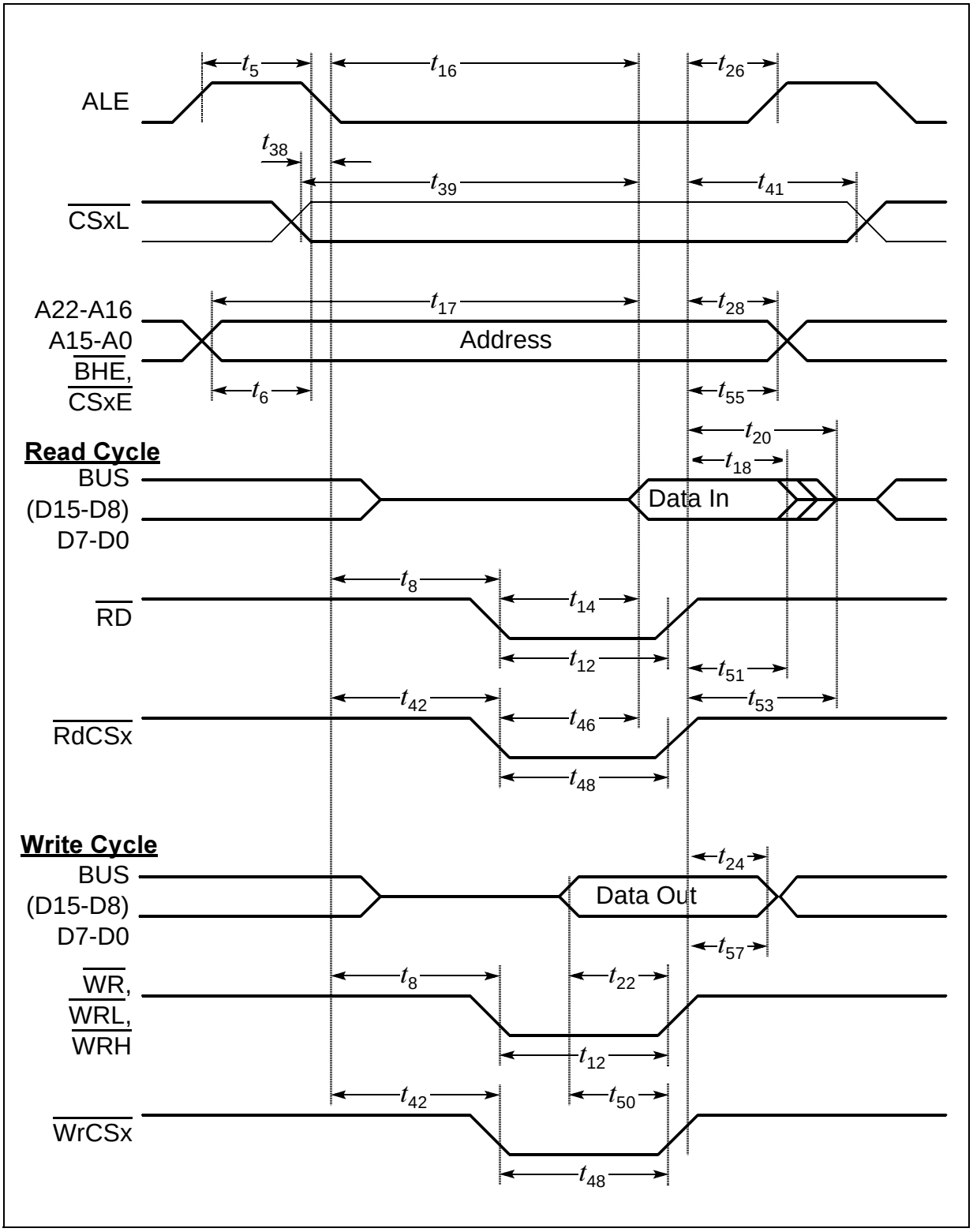

Figure 21 External Memory Cycle: Demultiplexed Bus, With Read/Write Delay, Extended ALE

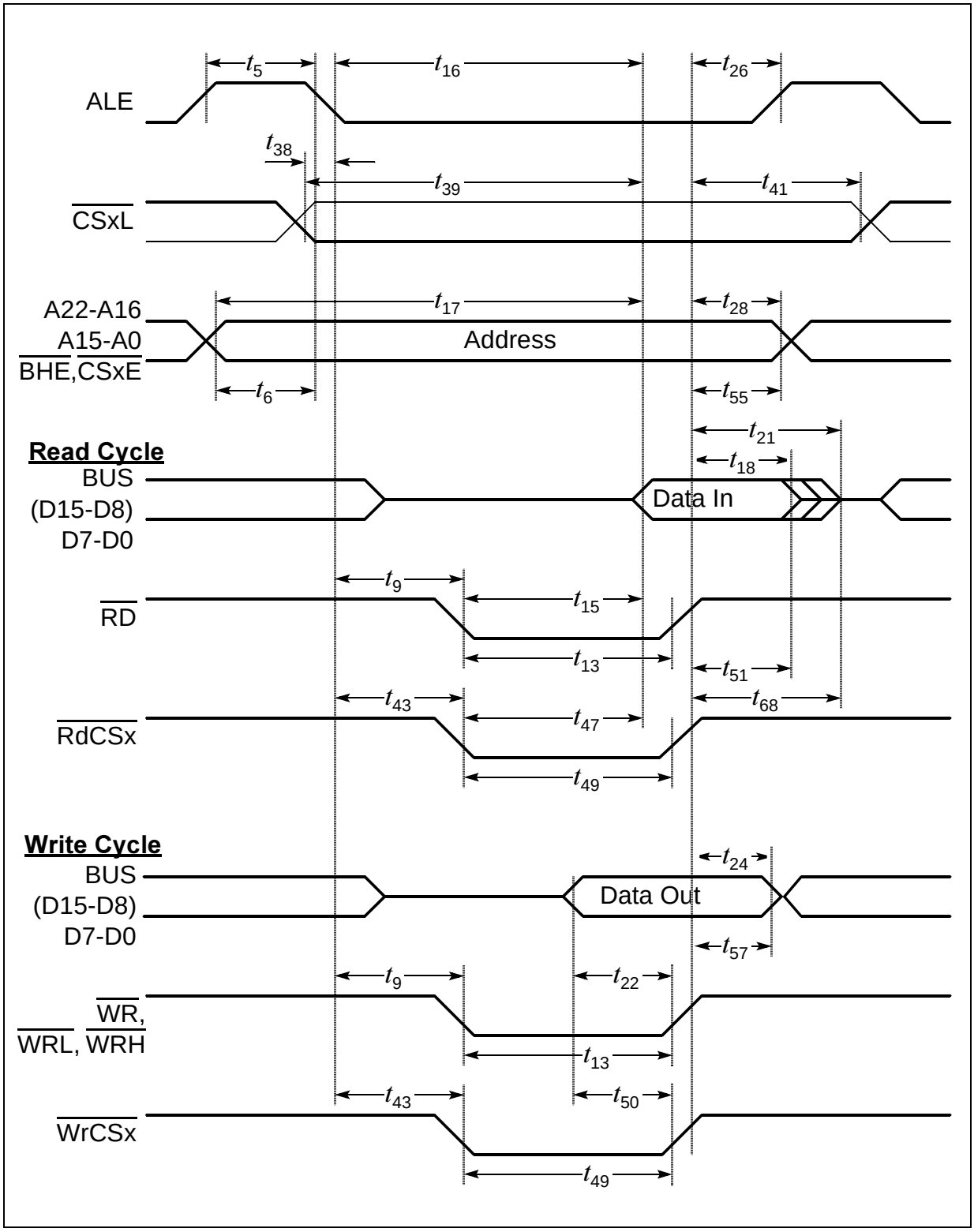

Figure 23 External Memory Cycle: Demultiplexed Bus, No Read/Write Delay, Extended ALE

AC Characteristics

CLKOUT and $\overline{\text{READY}}$ (Reduced Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol		Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
			min.	max.	min.	max.	
CLKOUT cycle time	t_{29}	CC	40	40	2TCL	2TCL	ns
CLKOUT high time	t_{30}	CC	15	–	TCL – 10	–	ns
CLKOUT low time	t_{31}	CC	13	–	TCL – 12	–	ns
CLKOUT rise time	t_{32}	CC	–	12	–	12	ns
CLKOUT fall time	t_{33}	CC	–	8	–	8	ns
CLKOUT rising edge to ALE falling edge	t_{34}	CC	$0 + t_A$	$8 + t_A$	$0 + t_A$	$8 + t_A$	ns
Synchronous $\overline{\text{READY}}$ setup time to CLKOUT	t_{35}	SR	18	–	18	–	ns
Synchronous $\overline{\text{READY}}$ hold time after CLKOUT	t_{36}	SR	4	–	4	–	ns
Asynchronous $\overline{\text{READY}}$ low time	t_{37}	SR	68	–	$2TCL + t_{58}$	–	ns
Asynchronous $\overline{\text{READY}}$ setup time [1]	t_{58}	SR	18	–	18	–	ns
Asynchronous $\overline{\text{READY}}$ hold time [1]	t_{59}	SR	4	–	4	–	ns
Async. $\overline{\text{READY}}$ hold time after $\overline{\text{RD}}$, $\overline{\text{WR}}$ high (Demultiplexed Bus) [2]	t_{60}	SR	0	$0 + 2t_A + t_C + t_F$ [2]	0	$\text{TCL} - 25 + 2t_A + t_C + t_F$ [2]	ns

1) These timings are given for test purposes only, in order to assure recognition at a specific clock edge.

2) Demultiplexed bus is the worst case. For multiplexed bus 2TCL are to be added to the maximum values. This adds even more time for deactivating $\overline{\text{READY}}$.
The $2t_A$ and t_C refer to the next following bus cycle, t_F refers to the current bus cycle.
The maximum limit for t_{60} must be fulfilled if the next following bus cycle is $\overline{\text{READY}}$ controlled.